2309409-4 ACTIVE

DDR4 DIMM

TE Internal #: 2309409-4

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount,

Cable-to-Board, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM SOCKETS



DRAM Type: Small Outline (SO)
Stack Height: 5.2 mm [.205 in]
Module Orientation: Right Angle
PCB Mounting Style: Surface Mount
Connector System: Cable-to-Board

All DDR4 SO DIMM SOCKETS (39)

Features

Product Type Features

Center Post	Without
DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Center Key	Offset Left
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	260
Number of Rows	2
Keying	Standard
Electrical Characteristics	

1.2 V

Signal Characteristics

DRAM Voltage



SGRAM Voltage	1.2 V
Body Features	
Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Retention Post Location	Both Ends
Module Key Type	Offset Left
Ejector Type	Locking
Connector Profile	Low
Contact Features	
Socket Style	SO DIMM
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card
Termination Features	
Insertion Style	Cam-In
Mechanical Attachment	
Mechanical Attachment PCB Mount Retention	With
	With Solder Peg
PCB Mount Retention	
PCB Mount Retention PCB Mount Retention Type	Solder Peg
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style	Solder Peg Surface Mount
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type	Solder Peg Surface Mount
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features	Solder Peg Surface Mount Board Mount
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features Centerline (Pitch)	Solder Peg Surface Mount Board Mount .5 mm[.02 in]
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features Centerline (Pitch) Housing Color	Solder Peg Surface Mount Board Mount .5 mm[.02 in] Black
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features Centerline (Pitch) Housing Color Housing Material	Solder Peg Surface Mount Board Mount .5 mm[.02 in] Black
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features Centerline (Pitch) Housing Color Housing Material Dimensions	Solder Peg Surface Mount Board Mount .5 mm[.02 in] Black High Temperature Thermoplastic
PCB Mount Retention PCB Mount Retention Type PCB Mounting Style Connector Mounting Type Housing Features Centerline (Pitch) Housing Color Housing Material Dimensions Stack Height	Solder Peg Surface Mount Board Mount .5 mm[.02 in] Black High Temperature Thermoplastic 5.2 mm[.205 in]



Operation/Application

Circuit Application	Power
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tape & Reel
Packaging Quantity	800

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | DDR4 DIMM

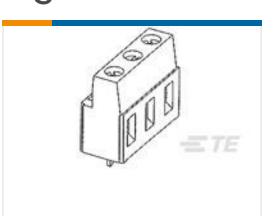






Customers Also Bought





TE Part #282844-3 TERMI-BLOK PCB MOUNT 90 3P.



TE Part #1734366-1 Std USB Type A, VT, T/H





TE Part #8-1614882-1 CPF 0603 360K 0.1% 25PPM 5K RL



TE Part #1-1337582-0 MCX SMT Skt 50Ohm Gold Pltd



TE Part #5-1625867-0 RP 1J 0.166W 20R 0.1% 25PPM 1K RL







Documents

Product Drawings

DDR4 SODIMM 260P 5.2H STD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309409-4_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309409-4_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309409-4_1.3d_stp.zip

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English